

# Harvatek Surface Mount LED Data Sheet T1551DND-60P000712U1930

Official Product	HT Part No. T1551DND-60P000712U1930					
Tentative Product	*******					
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 1/16		



DISCLAIMER	3
LIFE SUPPORT POLICY	3
PRODUCT SPECIFICATIONS	4
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION	4
LABEL SPECIFICATIONS	5
SPECIFICATIONS RANGE	6
PRODUCT FEATURES	8
ELECTRO-OPTICAL CHARACTERISTICS	8
PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR REFLO	
SOLDERING	
ABSOLUTE MAXIMUM RATINGS	
CHARACTERISTICS OF T1551DND	9
PRECAUTION FOR USE	10
PACKAGING	11
TAPE DIMENSION	11
REEL DIMENSION	12
Packing	12
DRY PACK	13
Baking	13
Precautions	13
HANDLING OF SILICONE RESIN LEDS	14
REFLOW SOLDERING	15
Reworking	15
CLEANING	15
CAUTIONS OF PICK AND PLACE	16
REVISE HISTORY	16

Official Product	HT Part No. T1551DND-60P000712U1930					
Official Floudet	HT Part No. 11551DND-60P00071201930					
Tentative Product	*******					
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 2/16		



#### **DISCLAIMER**

HARVATEK reserves the right to make changes without further notice to any products herein to improve reliability, function or design. HARVATEK does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

### **Life Support Policy**

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

7						
Official Product	HT Part No. T1551DND-60P000712U1930					
Tentative Product	*******					
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 3/16		



#### **Product Specifications**

Item	Specification	Material	Quantity
11.7	19.33-26.82 lm		
IV	@60mA / $T_s$ = 25 $^{\circ}$ C; Tolerance: ±10%		
Chromaticity	As page 6~7		
Coordinate	@60mA/ $T_S$ = 25 $^{\circ}$ C; Tolerance: ±0.005		
Vf	2.8~3.4 V (0.1V/Bin)		
	@60mA/ $T_S$ = 25°C; Tolerance: ±0.05V		
Ir	< 10 μA @ V <sub>R</sub> = 5 V		
CRI	CRI>80, Tolerance± 2		
Resin	Yellow	Silicone Resin	
Carrier tape	EIA 481-1A specs	Conductive black tape	
Reel	EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	250x230mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

#### Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, CIE and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note: This is shipped test conditions

\*Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

#### ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlGaInP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

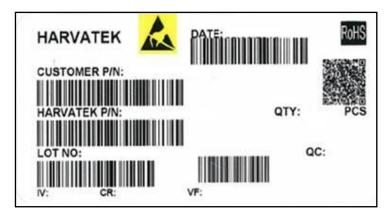
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Official Product HT Part No. T1551DND-60P000712U1930						
Tentative Product	*******					
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 4/16		



# **Label Specifications**



### Harvatek P/N:

T 155 1 DND- 60P- 0007 12

Product	Package	Dice Qty	Color	Current	Series Number	Taping
LF	3.1(L)x2.1(W)x0.8(H) mm	1:Single	DND: White,	60mA	X001~XZZZ	1.Taping style
			CRI>80			2. Qty

## Lot No.:

1 2	3	4	5	6	7	8	9	10
E 1	Α	1	Α	2	2	L	1	2
Code 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	9
Internal Tracing Code	2020-L 2021-M 2022-P 2023-Q  2026-T 2027-V  2030-Y 2031-Z	1:Jan. 2:Feb.  A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C  26:Z 27:7 28:8 29:9 30:3 31:4	01-	-ZZ		000~ZZZ	

Official Product	HT Part No. T1551DND-60P000712U1930						
Tentative Product	*******						
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 5/16			



# **Specifications Range**

# (Iv) Bin:

Color	Bin Code	Spec. Range
	NB1	19.33-20.62 lm
	NC2	20.62-22.02 lm
DND	ND2	22.02-23.50 lm
	AP1	23.50-25.10 lm
	BP1	25.10-26.82 lm

Note: It maintains a tolerance of ±10% on IV

# **■**Color Bin:

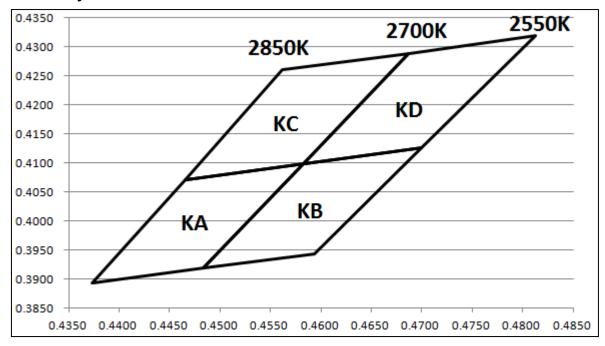
Color	Bin Code	Х	Y	Bin Code	Х	Y
		0.4373	0.3893		0.4465	0.4071
		0.4465	0.4071		0.4562	0.4260
	KA	0.4582 0.4099 KC	KC	0.4687	0.4289	
		0.4483	0.3919		0.4582	0.4099
DND		0.4373	0.3893		0.4465	0.4071
DND		0.4483	0.3919		0.4582	0.4099
		0.4582	0.4099		0.4687	0.4289
	КВ	0.4700	0.4126	KD	0.4813	0.4319
		0.4593	0.3944		0.4700	0.4126
		0.4483	0.3919		0.4582	0.4099

Note: It maintains a tolerance of x,y  $\pm 0.005$ 

Official Product	HT Part No. T1551DND-60P000712U1930					
Tentative Product	*******					
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 6/16		



## **■**Chromaticity Coordinate



# ■Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range	
	H1	2.8-2.9V	
	H2	2.9-3.0V	
DND	H3	3.0-3.1V	
DND	H4	3.1-3.2V	
	J1	3.2-3.3V	
	J2	3.3-3.4V	

Note: It maintains a tolerance of ±0.05V on forward voltage measurements

7				
Official Product	HT Part No. T1551DND-60P000712U1930			
Tentative Product	********	*****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 7/16

05 00)



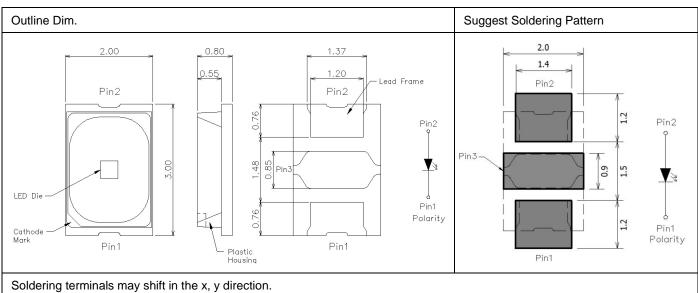
### **Product Features**

# **Electro-Optical Characteristics**

	I Soldering , 25 °C)						
Series	Emitting Color	Material	VF	(V)	Chromaticity Coordinate	I <sub>∨</sub> (Lm)	Viewing Angle
Series	Emitting Color	Malenai	typ max		x.y	Typical	$2\theta \frac{1}{2}$
T1551MND-60	Warm White	InGaN	2.8	3.4	x=0.4582,y=0.4099	22.76	120

## Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

Unit: mm Tolerance: +/-0.1



# **Absolute Maximum Ratings**

(T<sub>Soldering</sub> 25 °C)

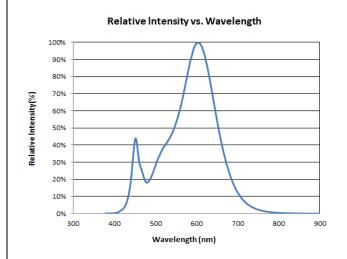
Series	P <sub>D</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)*	T <sub>OP</sub> (°C)	T <sub>ST</sub> (°C)
Color	Dower Discipation	Forward Current	Pulse Forward	Operating	Storage
Color	Power Dissipation	Forward Current	Current	Temperature	Temperature
DND	204	60	70	-40~+85	-40~+100

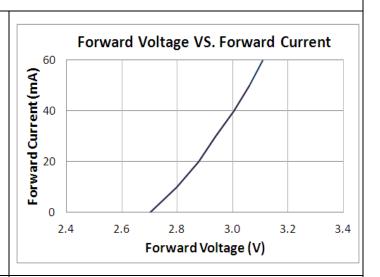
 $<sup>^{\</sup>star}$  Condition for IFP is pulse of 1/10 duty and 0.1msec width

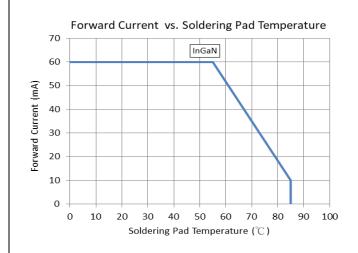
Official Product HT Part No. T1551DND-60P000712U1930				
Tentative Product	*******	******		
	t to changes for improvement without advance rawings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 8/16

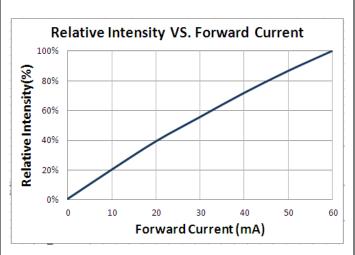


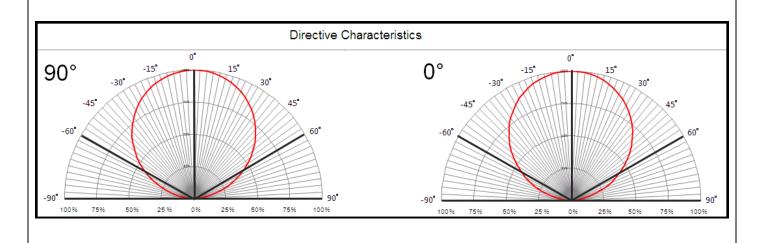
### **Characteristics of T1551DND**











Official Product	HT Part No. T1551DND-60P000712U1930			
Tentative Product	********	******		
	t to changes for improvement without advance awings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 9/16



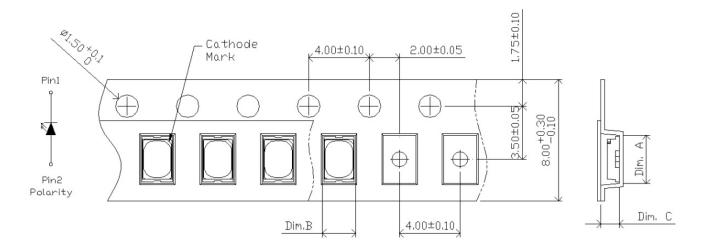
#### **Precaution for Use**

- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 4 weeks after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs.If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs.Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

7				
Official Product	HT Part No. T1551DND-60P000712U1930			
Tentative Product	********	******		
	t to changes for improvement without advance awings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 10/16

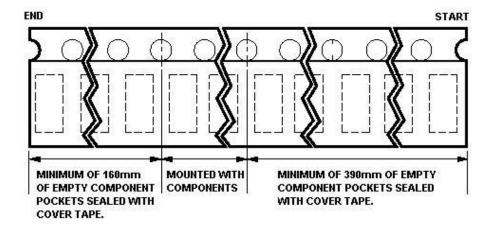


# Packaging Tape Dimension



Dim. A	Dim. B	Dim. C	Qty/Reel
3.18±0.1	2.18±0.05	1.00±0.05	2K

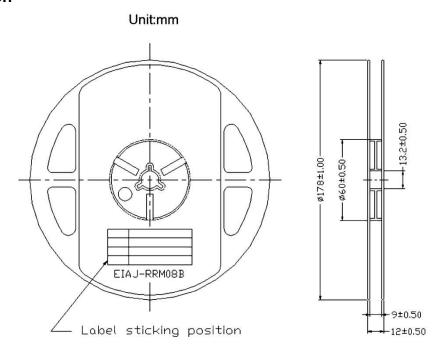
Unit: mm



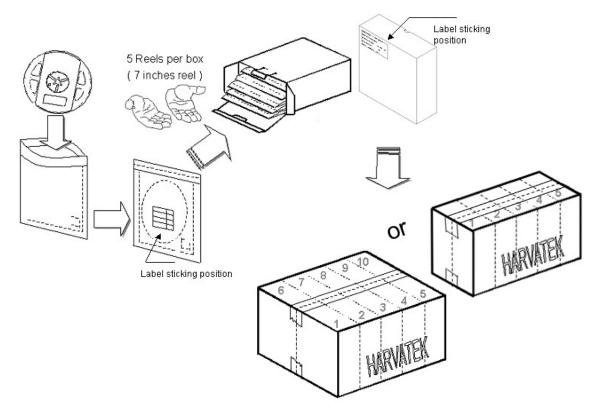
Official Product	HT Part No. T1551DND-60P000712U1930			
Tentative Product	*******	******		
	t to changes for improvement without advance awings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 11/16



### **Reel Dimension**



# **Packing**



5 or 10 boxes per carton is available depending on shipment quantity.

Official Product	HT Part No. T1551DND-60P000712U1930			
Tentative Product	*******	*****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 12/16

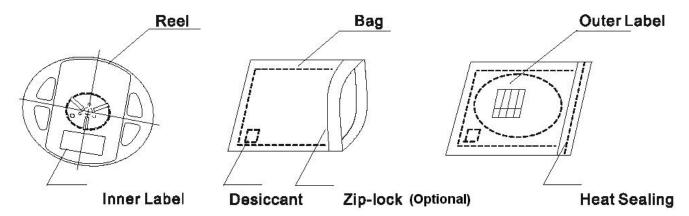


#### **Dry Pack**

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



## **Baking**

Baking before soldering is recommended when the package has been unsealed for 4 weeks. The conditions are as followings:

- 1.  $60\pm3^{\circ}$ C ×(12~24hrs)and<5%RH, taped reel type.
- 2.  $100\pm3^{\circ}$  × (45min~1hr), bulk type.
- 3.  $130\pm3^{\circ}$ C×(15min~30min), bulk type.

#### **Precautions**

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlGaInP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Official Product	HT Part No. T1551DND-60P000712U1930			
Tentative Product	*******	*****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 13/16



#### **Handling of Silicone Resin LEDs**

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible.

Sharp objects of all types should not be used to pierce the sealing compound.



Figure 1

In general, LEDs should only be handled from the side. By the way ,this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

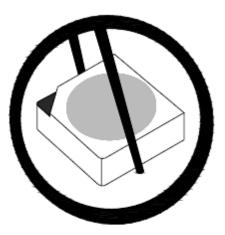


Figure 2

When populating boards in SMT production, there are basically no restrictions regarding the from of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is large than LEDs reflector area.

Official Product	HT Part No. T1551DND-60P000712U1930			
Tentative Product	********	******		
	t to changes for improvement without advance rawings, company confidential all rights reserved.	04/13/2023	Version 1.0	Page 14/16

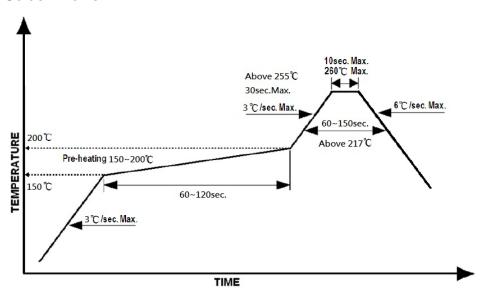


#### **Reflow Soldering**

Recommend soldering paste specifications:

- 1. Operating temp.: Above 217 °C ,60~150 sec.
- 2. Peak temp.:260 <sup>O</sup>CMax.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



#### Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

# Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter</li>
- Curing: 100 °C max, <3min

Official Product	HT Part No. T1551DND-60P000712U1930				
Tentative Product	********	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 15/16	



### **Cautions of Pick and Place**

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

## **Revise History**

Rev.	Descriptions	Date	Page
-	Preliminary	01/13/2023	-
1.0	Official Version	04/13/2023	-

Official Product	HT Part No. T1551DND-60P000712U1930				
Tentative Product	********	********			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		04/13/2023	Version 1.0	Page 16/16	